

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-20. (Canceled)

21. (Currently amended) A semiconductor device manufacturing method comprising:  
preparing an assembling apparatus comprising a cover, having an opening therein,  
provided on a setting base comprising a heating function;  
setting a plate-like substrate having conductive patterns mounted on the setting base; and  
mounting a semiconductor chip to the substrate or wire-bonding electrodes of the  
semiconductor chip to the conductive patterns through the opening,  
wherein an illumination is disposed above the opening and a blowing device is provided  
at a periphery part of the illumination in order to prevent a fluctuation of an inert gas generated  
by the heating function ~~from entering inside the illumination~~ upon mounting or wire-bonding the  
semiconductor chip.

22. (Currently amended) The semiconductor device manufacturing method of claim 21,  
wherein the blowing device provides a blow current to ~~escape~~ prevent the fluctuation.

23. (Previously presented) The semiconductor device manufacturing method of claim  
22, wherein the fluctuation escapes in a horizontal direction.

24. (Previously presented) The semiconductor device manufacturing method of claim  
21, wherein a part of the cover is formed as a clasper.

25. (Previously presented) The semiconductor device manufacturing method of claim 24, wherein the inert gas is blown inside the cover through the clamper.

26. (Previously presented) The semiconductor device manufacturing method of claim 21, herein the inert gas comprises nitrogen gas.

27. (Previously presented) The semiconductor device manufacturing method of claim 21, wherein a lens barrel is disposed above the illumination.

28. (Previously presented) The semiconductor device manufacturing method of claim 21, wherein a pattern recognition camera is disposed in the lens barrel.

29. (Previously presented) The semiconductor device manufacturing method of claim 21 wherein the blowing device is located in an area between the illumination and the cover near the opening.

30. (New) The semiconductor device manufacturing method according to claim 21, wherein the plate-like substrate has a plurality of blocks on each of which a plurality of mounting parts is formed.